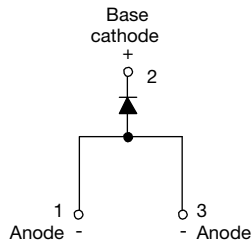


Surface Mount Fast Soft Recovery Rectifier Diode, 20 A


 TO-263AB (D²PAK)


FEATURES

- Glass passivated pellet chip junction
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

APPLICATIONS

- Output rectification and freewheeling in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

DESCRIPTION

The VS-20ETF..SPbF soft recovery rectifier series has been optimized for combined short reverse recovery time and low forward voltage drop.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

PRODUCT SUMMARY	
Package	TO-263AB (D ² PAK)
$I_{F(AV)}$	20 A
V_R	800 V, 1000 V, 1200 V
V_F at I_F	1.31 V
I_{FSM}	355 A
t_{rr}	95 ns
T_J max.	150 °C
Diode variation	Single die
Snap factor	0.6

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	20	A
V_{RRM}		800 to 1200	V
I_{FSM}		355	A
V_F	20 A, $T_J = 25$ °C	1.31	V
t_{rr}	1 A, 100 A/ μ s	95	ns
T_J	Range	-40 to +150	°C

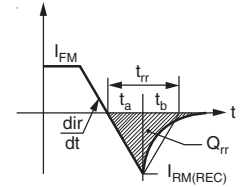
VOLTAGE RATINGS			
PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
VS-20ETF08SPbF	800	900	6
VS-20ETF10SPbF	1000	1100	
VS-20ETF12SPbF	1200	1300	

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 97$ °C, 180° conduction half sine wave	20	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	300	
		10 ms sine pulse, no voltage reapplied	355	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	450	A ² s
		10 ms sine pulse, no voltage reapplied	635	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	6350	A ² \sqrt{s}



ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	20 A, $T_J = 25\text{ }^\circ\text{C}$		1.31	V
Forward slope resistance	r_t	$T_J = 150\text{ }^\circ\text{C}$		11.88	m Ω
Threshold voltage	$V_{F(TO)}$			0.93	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^\circ\text{C}$		6	

RECOVERY CHARACTERISTICS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Reverse recovery time	t_{rr}	I_F at 20 A _{pk} 25 A/ μ s 25 $^\circ\text{C}$	400	ns
Reverse recovery current	I_{rr}		6.1	A
Reverse recovery charge	Q_{rr}		1.7	μC
Snap factor	S		Typical	0.6



THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +150	$^\circ\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	0.9	$^\circ\text{C/W}$
Maximum thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		62	
Soldering temperature	T_S		260	$^\circ\text{C}$
Approximate weight			2	g
			0.07	oz.
Marking device		Case style TO-263AB (D ² PAK)	20ETF08S	
			20ETF10S	
			20ETF12S	

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μ m) copper 40 $^\circ\text{C/W}$
For recommended footprint and soldering techniques refer to application note #AN-994

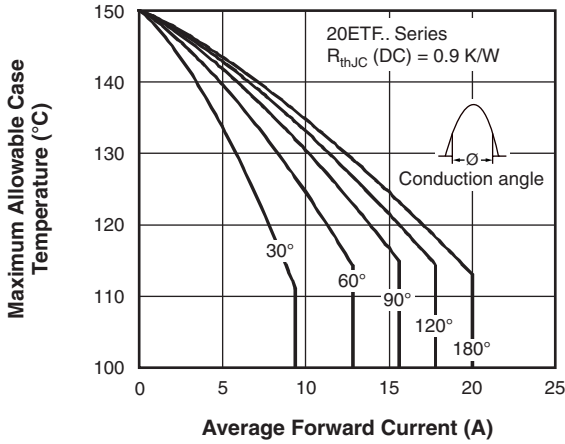


Fig. 1 - Current Rating Characteristics

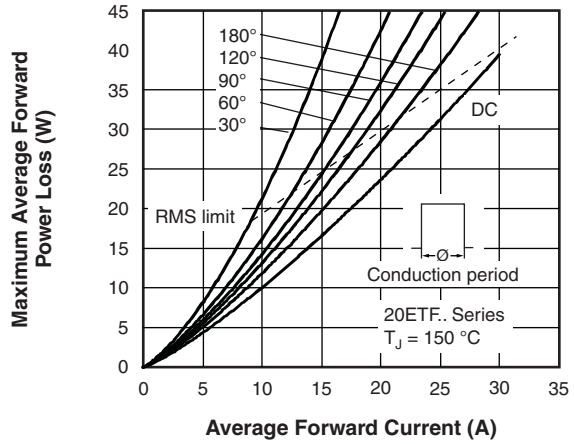


Fig. 4 - Forward Power Loss Characteristics

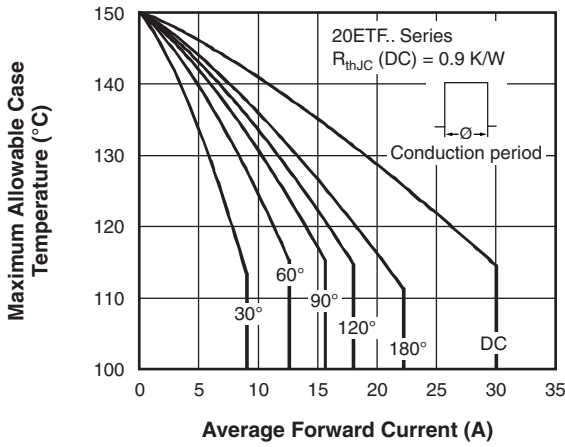


Fig. 2 - Current Rating Characteristics

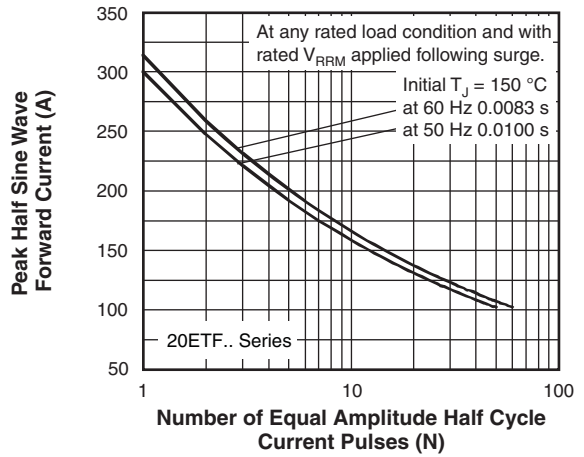


Fig. 5 - Maximum Non-Repetitive Surge Current

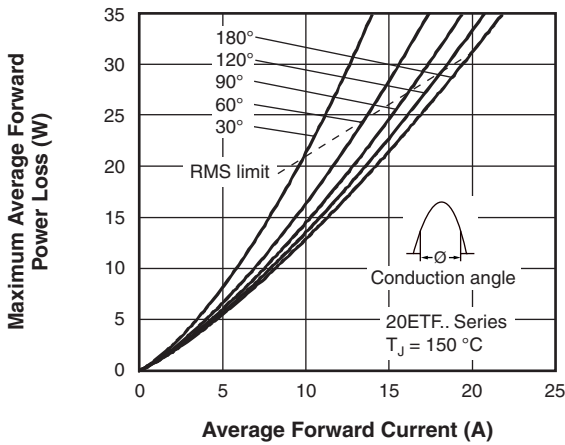


Fig. 3 - Forward Power Loss Characteristics

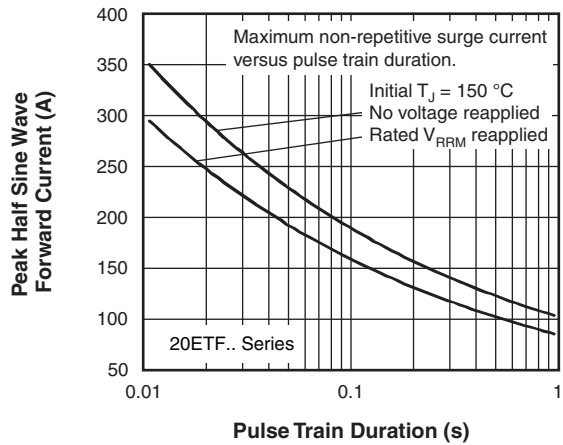


Fig. 6 - Maximum Non-Repetitive Surge Current

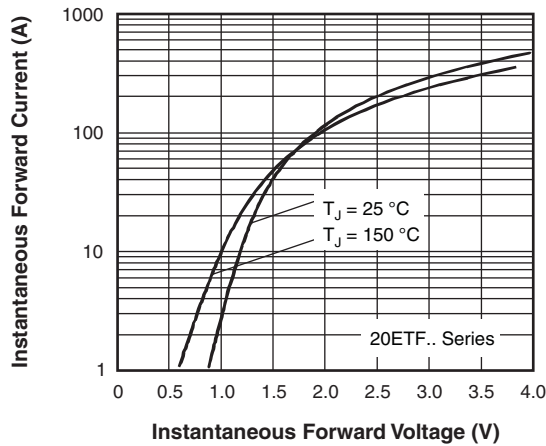


Fig. 7 - Forward Voltage Drop Characteristics

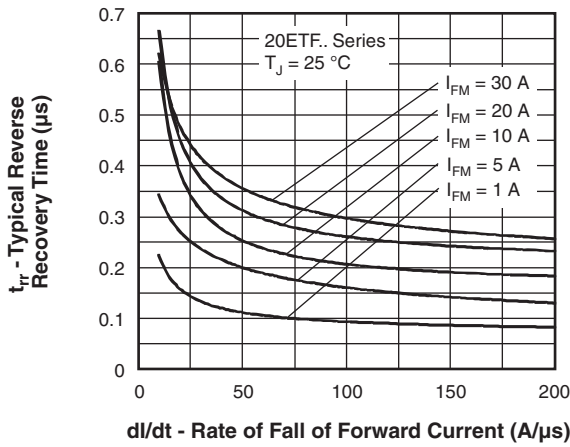


Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ °C}$

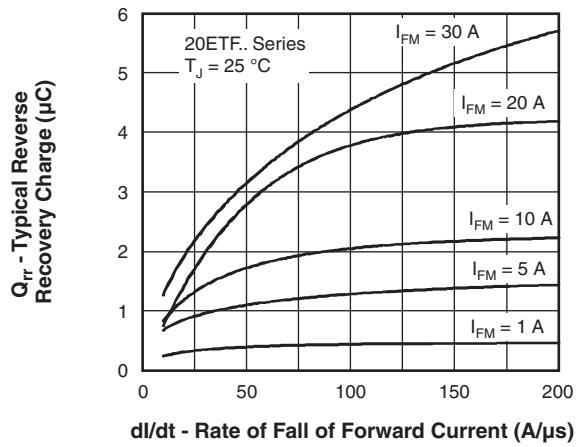


Fig. 10 - Recovery Charge Characteristics, $T_J = 25\text{ °C}$

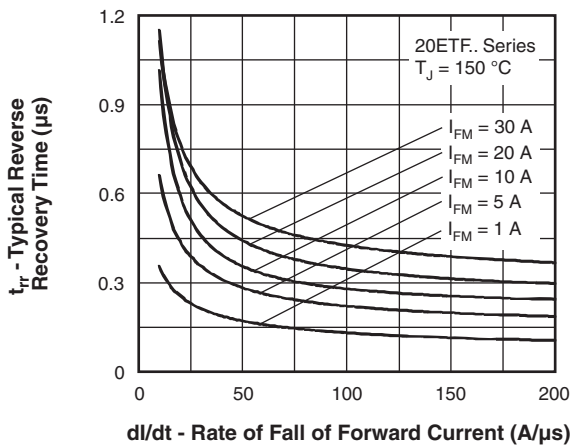


Fig. 9 - Recovery Time Characteristics, $T_J = 150\text{ °C}$

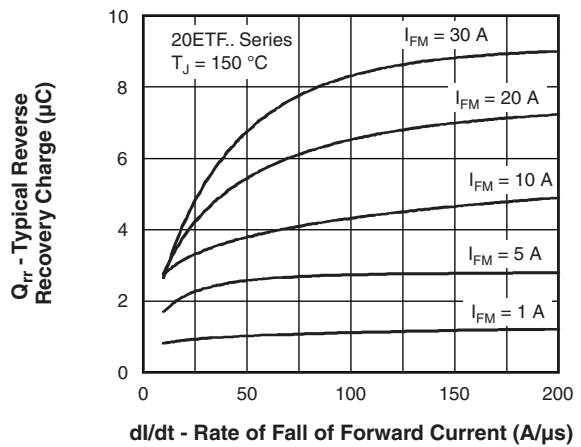


Fig. 11 - Recovery Charge Characteristics, $T_J = 150\text{ °C}$

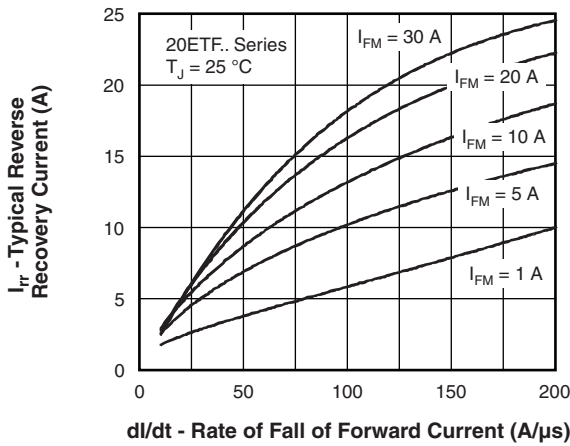


Fig. 12 - Recovery Current Characteristics, T_J = 25 °C

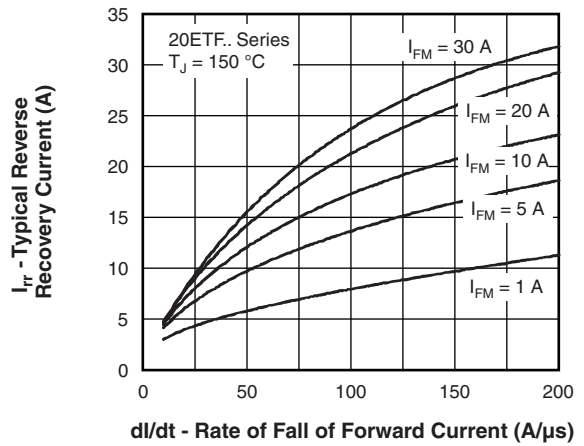


Fig. 13 - Recovery Current Characteristics, T_J = 150 °C

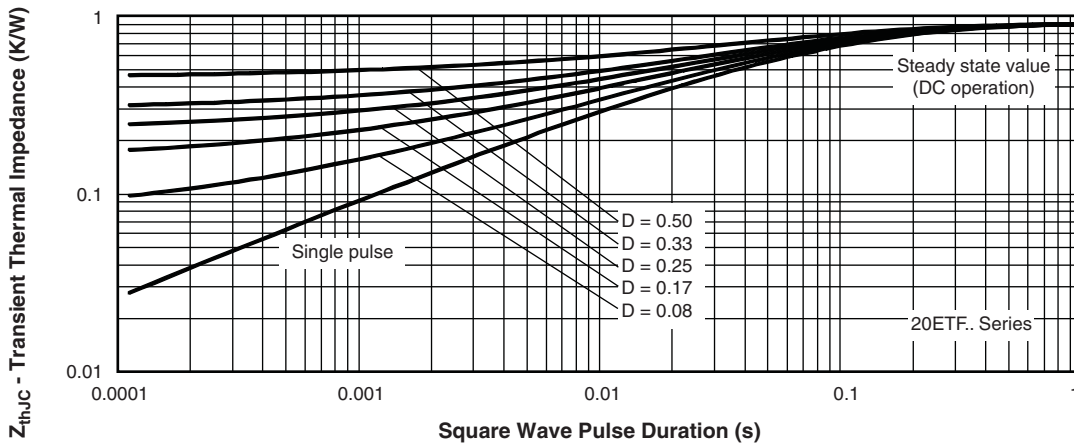
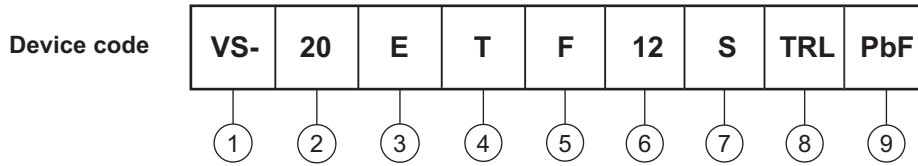


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (20 = 20 A)
- 3** - Circuit configuration:
E = single diode
- 4** - Package:
T = TO-263AB (D²PAK)
- 5** - Type of silicon:
F = fast soft recovery rectifier
- 6** - Voltage code x 100 = V_{RRM}
- 7** - S = surface mountable
- 8** -
 - None = tape
 - TRR = tape and reel (right oriented)
 - TRL = tape and reel (left oriented)
- 9** -
 - None = standard production
 - PbF = lead (Pb)-free

08 = 800 V
10 = 1000 V
12 = 1200 V

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-20ETF08SPbF	50	1000	Antistatic plastic tubes
VS-20ETF08STRRPbF	800	800	13" diameter reel
VS-20ETF08STRLPbF	800	800	13" diameter reel
VS-20ETF10SPbF	50	1000	Antistatic plastic tubes
VS-20ETF10STRRPbF	800	800	13" diameter reel
VS-20ETF10STRLPbF	800	800	13" diameter reel
VS-20ETF12SPbF	50	1000	Antistatic plastic tubes
VS-20ETF12STRRPbF	800	800	13" diameter reel
VS-20ETF12STRLPbF	800	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95054
Packaging information	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070		H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065		L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2	L4	4.78	5.28	0.188	0.208	

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB



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